

L Number	Hits	Search Text	DB	Time stamp
-	2	((("6281111") or ("6097091"))).PN.	USPAT	2002/11/01 09:32
-	8	((("6136624") or ("5382544") or ("4654113") or ("6051489") or ("5859472") or ("5659203") or ("5790377") or ("5828128"))).PN.	USPAT	2002/11/01 09:44
-	17	semiconductor and (package or packaging) and ((face near down) near technique)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:49
-	17	semiconductor and ((face near down) near technique) and electrode	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:55
-	44	toledo.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:51
-	0	((438/127).CCLS.) and (faced near down) same technique	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:55
-	0	((438/127).CCLS.) and ((faced near down) same technique)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:56
-	14	((438/127).CCLS.) and ((face near down) same technique)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 09:56
-	666	(438/127).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:00
-	0	((438/127).CCLS.) not(@ad>19970519 or rlad>19970519)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:01
-	210	((438/127).CCLS.) not (@ad>19970519 or @rlad>19970519)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:04
-	11	((("4597177") or ("5207887") or ("5346857") or ("5431328") or ("5477087") or ("5642261") or ("3795037") or ("4893172") or ("5518964") or ("5682061") or ("5763941"))).PN.	USPAT	2002/11/01 10:21
-	442	(438/108).CCLS.	USPAT	2002/11/01 10:21
-	577	(438/108).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:21
-	95	((438/108).CCLS.) not (@ad>19970519 or @rlad>19970519)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:55

-	15	semiconductor and ((dielectric or insulating or encapsulant) same (polyimide near resin)) and ((flip near chip) same (polyimide near resin))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 10:59
-	306	semiconductor and (polyimide near resin) and (flip near chip) and (package or packaging or packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:00
-	93	(semiconductor and (polyimide near resin) and (flip near chip) and (package or packaging or packaged)) not (@ad>19970519 or @rlad>19970519)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/01 11:01